



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PART NUMBER : 7311E0225S01001LF

GENERAL :

High cycle life duration smart card connector with landing type contacts mechanism. The landing type connector also provides the feature of recessed contacts when card is not inserted which protects them against vandalism.
Smart card for reference purposes only.

ELECTRICAL PROPERTIES:

Insulation resistance : > 1000MΩ
Dielectric withstanding voltage : > 750 Vrms
Current carrying capacity : Min 10μA, Max 1A
Contact resistance : < 100mΩ

MECHANICAL PROPERTIES :

Operating force : Insertion : F < 10N
Withdrawal : 1 < F < 10N
Contact Normal force : 0.2 < F < 0.3 for 0.6mm of deflection
Durability : 500,000 mating cycles

MATERIAL :

Head reader : High temp. Thermoplastic, Black, Rated UL94V0
Cover : High temp. Thermoplastic, Colour. Black, Rated UL94V0
Contacts : Copper alloy,
Plating : Nickel min. all over
Gold/Equivalent PdNi on contact area
Matte tin min. on solder tails

ENVIRONMENT :

Operating temperature : -40°C / +85°C
Climatic conditions : UTE 93-421

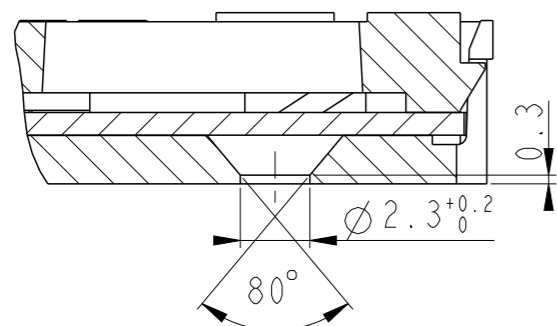
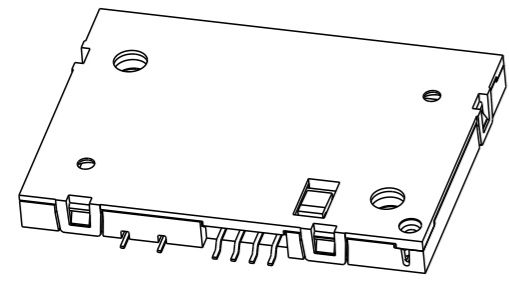
PACKAGING :

Plastic cavity tray

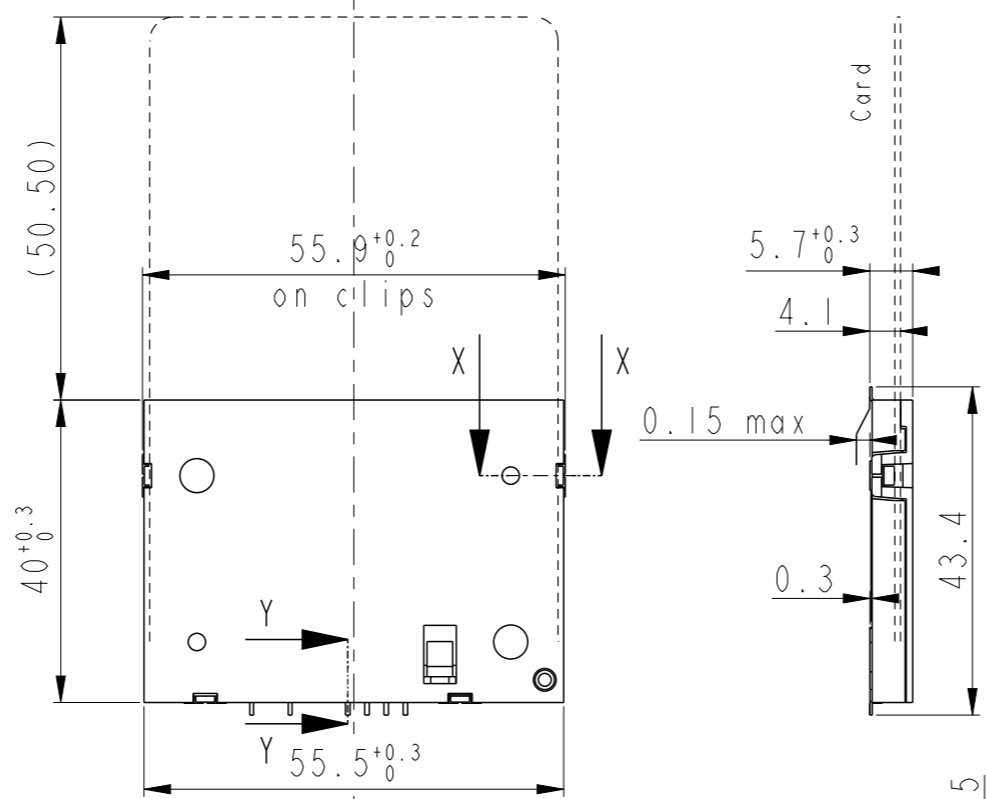
LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-47-0004"

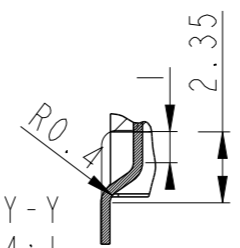
The housing will withstand exposure to 260°C peak temperature for 10seconds in a convection reflow oven.



SECTION X-X
SCALE 4:1

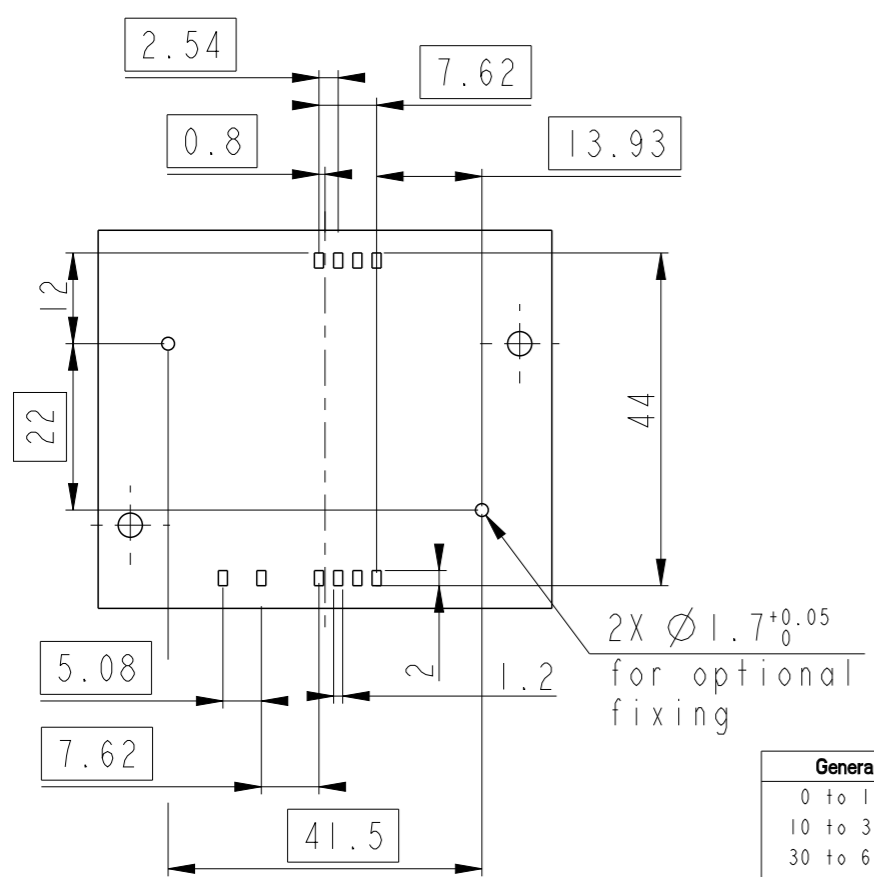


SECTION Y-Y
SCALE 4:1



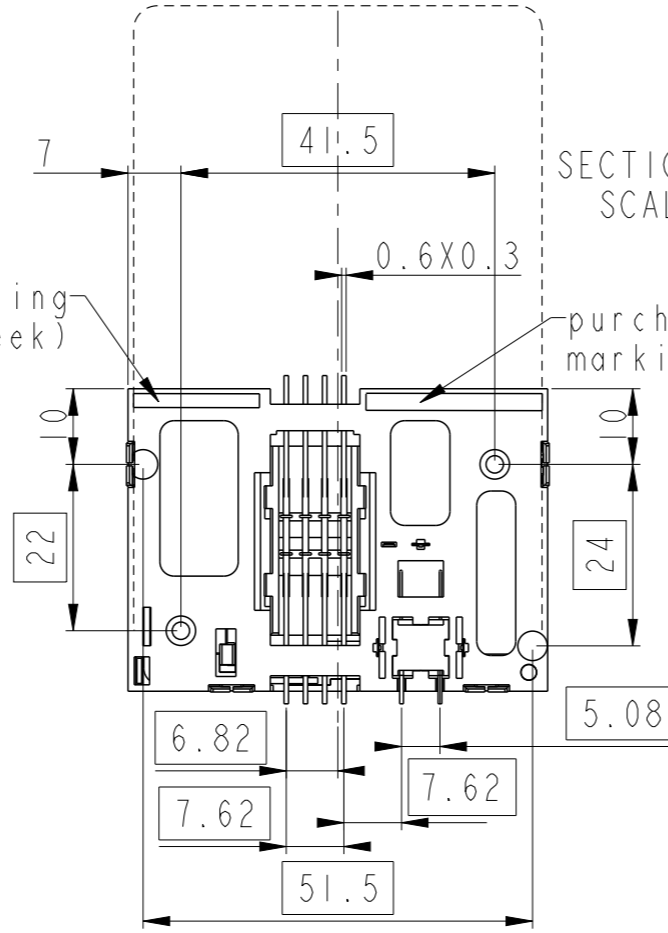
card insertion direction

Recommended PCB Layout (Component side)



manufacturing date (year-week)

purchase number marking



spec ref	--
tolerance std	ISO 406 ISO 1101
surface	ISO 1302

General Tolerances		
0 to 10mm:	±0.1mm	
10 to 30mm:	±0.15mm	
30 to 60mm:	±0.2mm	
60 and more:	±0.3mm	

TOLERANCES UNLESS OTHERWISE SPECIFIED		
linear	0.X	±
	0.XX	±
	0.XXX	±
angular	0°	±°

dr	P-Mathew Nebu	2014/02/26
eng	P-Mathew Nebu	2014/03/03
chr	-	-
appr	K-Paul Biju	2014/03/03



projection	mm	size	A3	scale	1:1
product family	MOBILE I/O	ecn no	-	rel level	Released
title	8 POS. SMT E02 WITHOUT PEGS		dwg no	10128659	rev
cat. no.	-	Product - Customer Drw	sheet 1 of 1		